

Specifications

Ultrasonic Flaw detector HIS 3 HF		
Pulse Output	-200V max (no load)	
Pulse Falling Time	1.0ns max	
Receiver Band Width	1.0 - 300MHz(-3dB)	
Gain Adjustable Range	0 - 71dB/1dB	
Beam Path Measurement	0 - 40.96 μ sec	
CPU Control	Parallel I/O, RS232C each one	
Scanner (Standard Six Axes Scanner)		
Scanning Range	X: 500mm -Y: 400mm -Z: 300mm R/turtable: ϕ 300 θ 1: 110°, θ 2: \pm 45°	
Scanning Speed	Max 300mm/sec	
Scanning Pitch	0.005 - 9.995mm (X - Y - Z) 0.02 - 9.98° (R: turtable)	
Scanning Mode	Plane, Side Face, Slope, Curved Face, Cylinder, Spherical Face, Continuous Rotation	
Water Tank Capacity	705mm W \times 655mm D \times 440mm H	
Other	Scanning Area Selection, Jog Dial Remote Controller	
Data Processing		
Data Collection Points	Max 40,000,000 points (per one scanning)	
Test Data Saving Drive	HDD, FDD, CD - RW	
Setup Parameter Reservation	HDD, FDD, CD - RW	
Image Processing Software	Contrast Display	2 color 256 contrast (arbitrarily selectable form 16 million colors including black and white) Color 16 contrast, RYB 256 contrast
	Echo Evaluation	Sound pressure contrast, depth contrast, MURAI contrast
	Real Time Processing	Plane image, cross sectional image, perspective image, 3D image, wire frame image, precise detection (zoom up test), measurement in image, enlargement, shifting to cursor position, area ratio, setup value display, echo height display, echo height perspective, selected points data collection
	LAN Access	
General Condition		
Dimensions	Console Desk: 1400mm W \times 800mm D \times 700mm H Six Axes Scanner: 1150mm W \times 1100mm D \times 1750mm H	
Weight	Console Desk: 150kg Six Axes Scanner: 350kg	
Power Supply	AC100V(\pm 10%) 1.5kVA	

Other Products



• Portable Phased Array Ultrasonic Testing System **PA4**



• Phased Array Ultrasonic Imaging System **PDS**

* Contents of this catalogue were based on December, 2014 and are subject to change without notice.
* The color of products shown in the pictures might be slightly different from the actual color.

Creating the future by INDES
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ISO 9001:2008



Certified Branch: Osaka Branch



Digital Ultrasonic Flaw Detector & Imaging System

SDS-WIN

Reference



KJTD Co., Ltd.

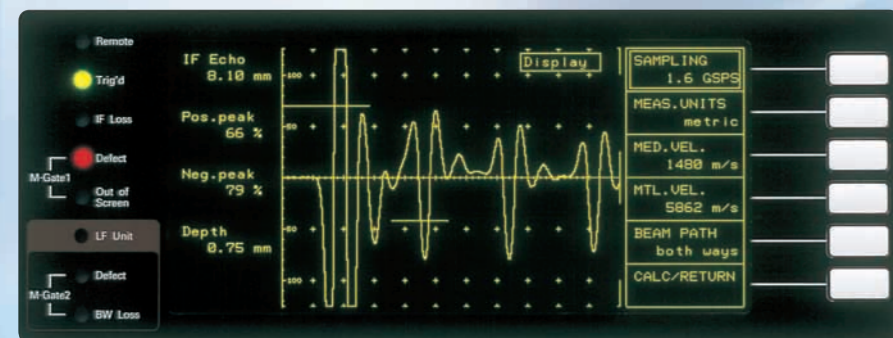
Ultrasonic Flaw Detector & Imaging System SDS-WIN

KJTD has developed SDS-WIN series with the latest ultrasonic detecting and image processing technology. This system is absolutely suitable for Aerospace, Steel, Non-Ferrous, Nuclear, Automobiles, New Materials, SemiConductor fields. SDS-win is completed with our newest edition, Ultrasonic Flaw Detector HIS3 and its Windows® operated system, makes the operation very simple and easy!



Ideal for New Materials-New Ultrasonic Flaw Detector HIS3

The high-speed and wide band ultrasonic flaw detector, model HIS3 HF/LF is a standalone type detector that integrates all necessary flaw detecting functions. This almighty detector is the most suitable for high-speed immersion detecting application.



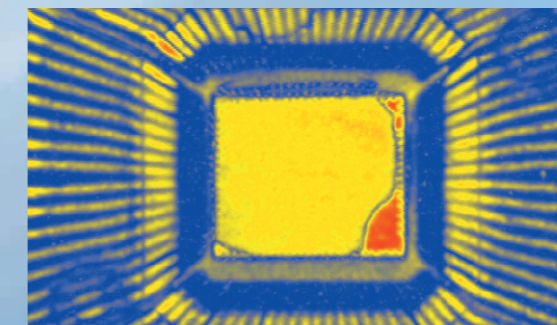
Latest Image Processing Technology

C-Scope or B & C-Scope can be viewed on real time during scanning. Analysis and evaluation can be executed by using our original image process engineering. Not only the ability to display echo height and path length, the results can be displayed with finalization, two colors, 16-color contrast, or versatile 256-contrast color gradation by our original MURAI. These results can be either printed out by a color printer or saved in the floppy disk or CD-RW disc. The display of the target defective point will be absolutely clear!

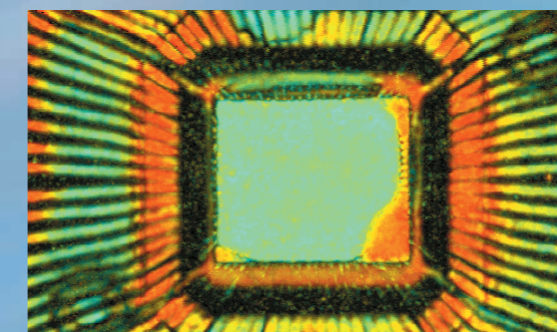
MURAI Processing

MURAI is our original software that evaluates the high damped waveform that is obtained from HIS3 and polymer probe by matrix processing technology. By evaluating echo strength and phase information, detecting of critical bond-errors or peel-offs and distinguishing of void or inclusion can be easily tested. MURAI is highly recommended for testing such as IC package testing. Patent No. : 2896385

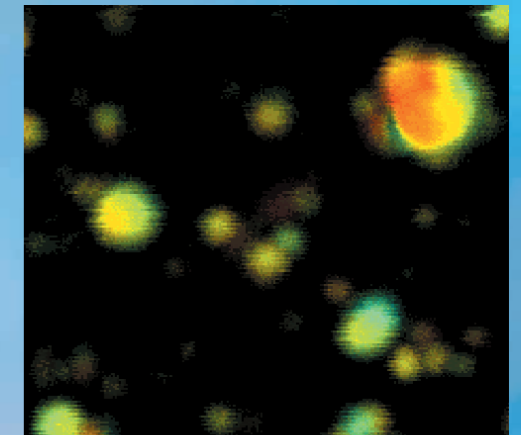
Inspection Example : Semiconductor/50MHz



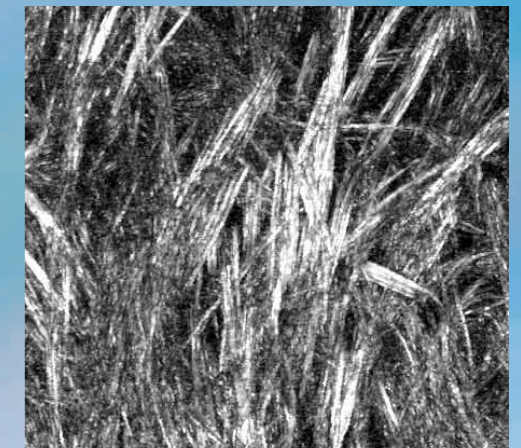
Normal Echo Height Evaluation



Bound-Error Detected by MURAI Software (red)



Voids (Red) and Inclusions (Blue) in Steel Materials/80MHz



Orientation Analysis of Glass Fiber Complex Materials/125MHz

Scanning pattern

Precise SDS Six axes scanner has various scanning patterns and its scanning areas can be simply chosen by selecting starting and ending points.

